

荣湃  
2PAI SEMICONDUCTOR

## 2PAI SEMICONDUCTOR COMPANY AND PRODUCT INTRODUCTION



ABOUT US



PRODUCT ROADMAP



PRODUCT APPLICATION SCENARIOS

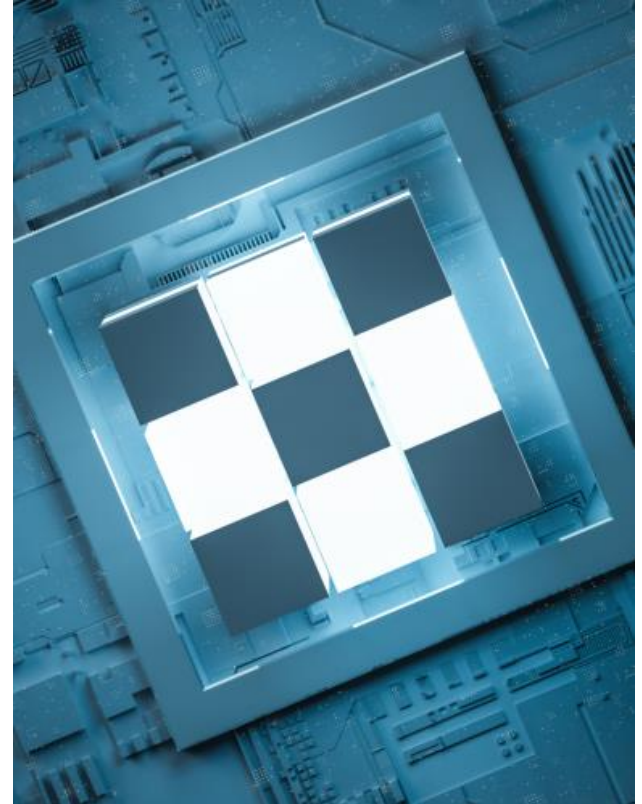
# Company Profile

Chips create new value

Founded in 2017, 2PAI Semiconductor (Shanghai) Co., Ltd. (hereinafter referred to as "2PAI Semiconductor" or the "company") is specialized in the design and development of high-performance and high-quality analog chips, with the commitment to becoming the world's leading supplier of high-performance analog integrated circuits.

The company's products including digital isolator, drive (MOSFET IGBT driver), interface (CAN, RS485), sample (amplifier, ADC), compatible optocoupler, etc are widely used in electric vehicles, industrial control, digital power, intelligent appliances and other fields, delivering performance and quality comparable to similar products of world-class analogue integrated circuit manufacturers, and even some superior key performance indicators. Relying on original capacitive voltage dividing technology (iDivider), we have been granted a great number of invention patents in isolation field, achieving the breakthrough of isolation chips made in China.

The R&D team of 2PAI Semiconductor brings together a large number of domestic and foreign analog chip field elites who boast advanced experience in analog integrated circuit design, process, testing technology, etc. Since its founding, the company has always been adhering to the guiding principle of **"chips create new value"**. We start from the nature of problems, explore new ways for troubleshooting, pay close attention to the change of market demand, attach great importance to innovation, provide high-quality and high-performance products to customers, spare no effort to promote the R&D and production of Chinese analog chips, propose new ideas to technical innovation of Chinese semiconductor industry, and create new value for the society.



## Company positioning

With products widely used in industrial control, new energy vehicles, digital power supply, intelligent appliances and other fields, we are committed to guiding the industrial upgrading and becoming the world's leading analog integrated circuit provider

1

## Product positioning

Bring in digital isolation to replace opto-isolators, drive conversion to products made in China; make greater efforts in developing "isolation+" products while extending to non-isolated cost-effective analog products.

3

## Technical innovation

With the proprietary **iDivider** technology and based on capacitive voltage dividing principle, transmit voltage signals from one side of capacitor to another side without RF signal and modem. Compared with other isolation technologies (Opto-Coupler, iCoupler, OOK, etc.) , this isolated signal transmission technology is more essential and concise.

2

## Technical advantages

- The circuit is simplified greatly with lower power consumption and higher speed
- Better anti-interference ability and lower noise
- Lower cost, higher cost effectiveness

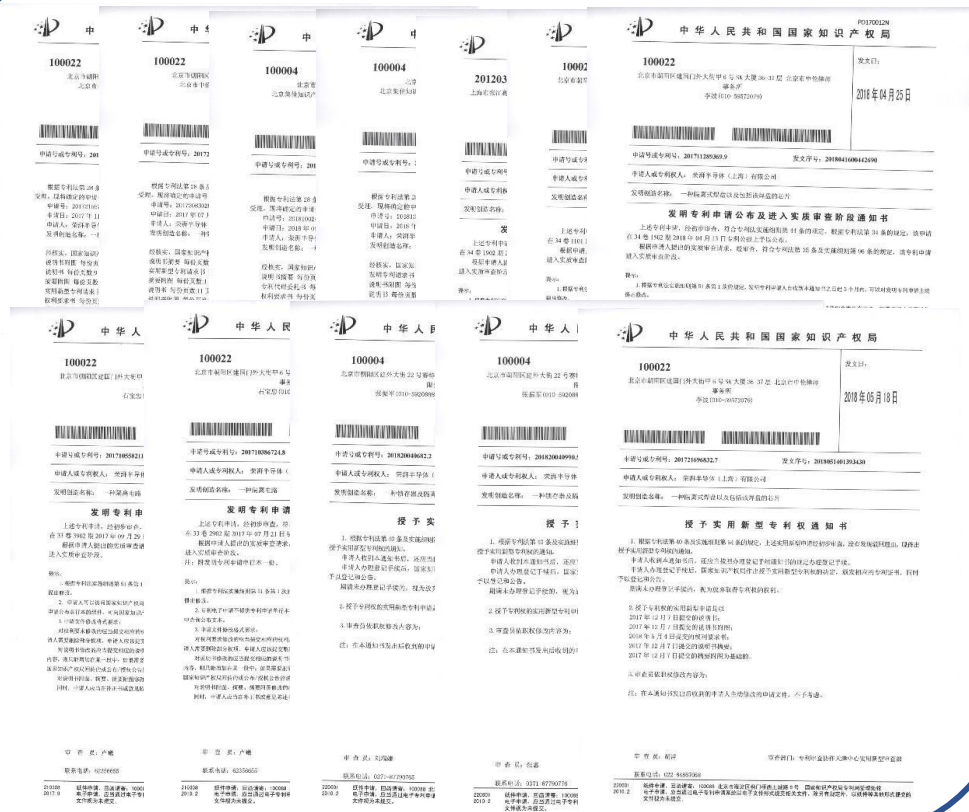
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**Independent R&D**  
**promoting the new development of industry**

## Chips create new value

**Company's original self-developed intelligent voltage dividing technology-iDivider™**

- 22 domestic and 11 international invention patents
- No intellectual property conflict with any company or individual in the world





# Certificate

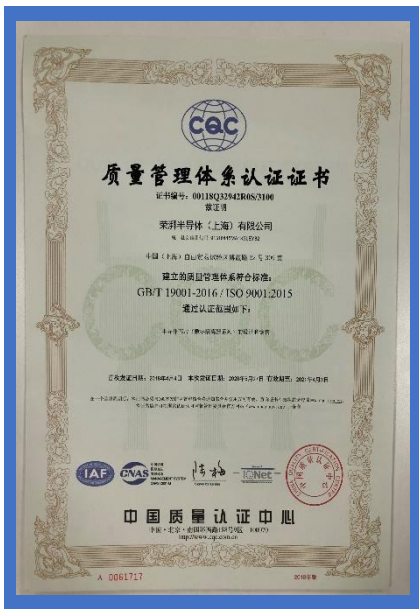
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## ISO9001

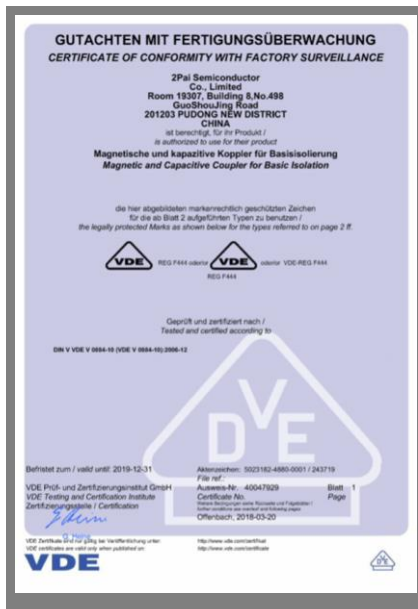
## VDE Certificate

## UL Certificate

## CQC Certificate



Date of obtaining the certificate for the first time: 4/4/2018



Date of obtaining the certificate for the first time: 3/20/2018



Date of obtaining the certificate: 10/26/2017



Date of obtaining the certificate: 4/23/2021

# Invention Patent of 2PAI Intelligent Voltage Dividing Technology-iDivider

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US010812027B2

## (12) United States Patent Dong

(10) Patent No.: US 10,812,027 B2  
(45) Date of Patent: Oct. 20, 2020

### (54) ISOLATION CIRCUIT

USPC ..... 330/59, 152  
See application file for complete search history.

(71) Applicant: 2PAI SEMICONDUCTOR CO.,  
LIMITED, Shanghai (CN)

(56)

### References Cited

#### U.S. PATENT DOCUMENTS

(72) Inventor: Zhiwei Dong, Shanghai (CN)

(73) Assignee: 2PAI SEMICONDUCTOR CO.,  
LIMITED, Shanghai (CN)

(\*) Notice: Subject to any disclaimer, the term of this  
patent is extended or adjusted under 35  
U.S.C. 154(b) by 0 days.

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2019/0156458 A1 \* 5/2019 Innocent ..... G06T 3/4023

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H03K 19/0175 (2006.01)  
H03F 3/45 (2006.01)  
H01G 4/38 (2006.01)  
H03F 3/387 (2006.01)

(52) U.S. Cl.  
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(2013.01); H03F 3/387 (2013.01); H03F  
3/45475 (2013.01); H03F 3/45928 (2013.01);  
H03K 19/017545 (2013.01); H03F 2200/271

Primary Examiner — Henry Choe  
(74) Attorney, Agent, or Firm — Adverso IP

(57)

### ABSTRACT

An isolation circuit and a method for providing isolation between two dies are provided. The isolation circuit includes: an isolation module, configured to generate an isolation signal based on an input signal from a first die and to provide isolation between the first die and a second die, where the isolation signal is smaller than the input signal in amplitude, and the first die is coupled with the second die; a latch module, configured to latch the isolation signal at a certain level and output a latched signal; an amplifier module, configured to amplify the latched signal. In the

证书号第 3541302 号

证书号第 39541

证书号第 3920155

证书号第 3419842

证书号第 3746703 号

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发明专利证书

发明名称: 一种

发明名称: -

发明名称: 一种

发明名称: 一

发明名称: 一种信息检测电路及方法

发明人: 张小

发明人: 1

发明人: 廖定

发明人: 张

发明人: 董志伟

专利号: ZL 20

专利号: 2

专利号: ZL 2

专利号: ZL

专利号: ZL 2017 1 1284421.1

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专利申请日: 2

专利申请日: 2019

专利申请日: 201

专利申请日: 2017 年 12 月 07 日

专利权人: 荣

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专利权人: 荣湃半导体 (上海) 有限公司

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守敬路 498 号 8 幢 19307 室

授权公告日: 2019

授权公告日: 2

授权公告日: 2020

授权公告日: 201

授权公告日: 2020 年 04 月 07 日 授权公告号: CN 108020792 B

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# Company Management

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**Dong Zhiwei**  
CEO



TEXAS  
INSTRUMENTS



SILICON LABS

Qualcomm

**Liu Qingguang**  
Independent partner



**Feng Xuwei**  
Director of Operations



life, augmented

**Dong Shuangbing**  
Director of Technology



UAES

**Cui Shize**  
Director of Finance



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TEXAS  
INSTRUMENTS



maxim  
integrated.



**Hu Yongjun**  
Vice President of Sales



**Zhang Xiaolong**  
Director of R&D



HUAWEI



The Future in Motion



ASE GROUP



地平线  
Horizon Robotics



**Zhao Nan**  
Director of Quality

Qualcomm



freescale



**Shi Yiya**  
Director of HR



酷维阿科技



**Wu Xinxia**  
CEO Assistant  
Director of General Affairs



## Company's operating revenue



Unit: \$ Million

**35%** of operating revenue  
is from electric vehicle customers

Cooperate with China's top manufacturers to create  
quality and reliable products

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### Wafer tape-out



(TSMC subsidiary)



### Package test



Sufficient production capacity  
8-12 week delivery cycle

# Performance advantages of isolation products

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## Low power consumption

A major concern to customers of battery management system, instrument and apparatus

## U series cost-effective product (150Kbps)

A major concern to low-rate and cost-valuing customers

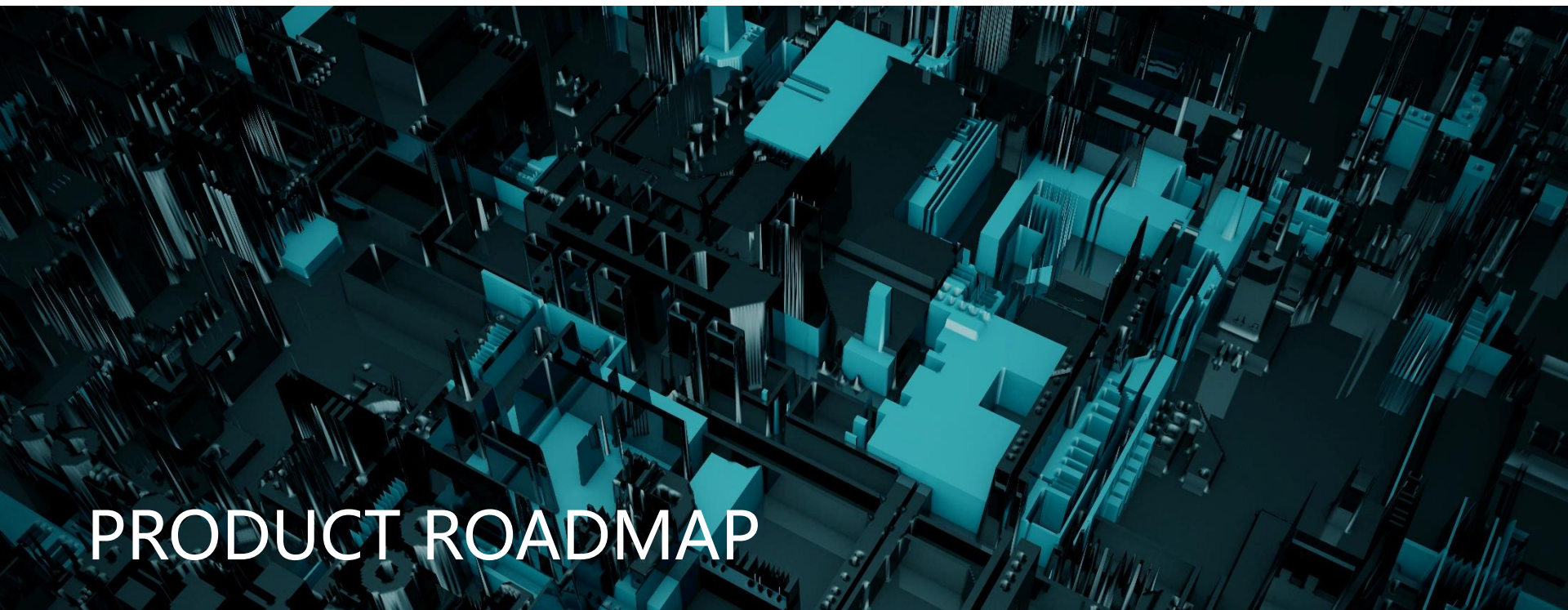


## Low latency and low pulse width distortion

A major concern to customers of digital power/motor drive

## PIN TO PIN compatible with foreign mainstream isolation products

Prevent customers from redrawing PCB



# PRODUCT ROADMAP

# Product Roadmap

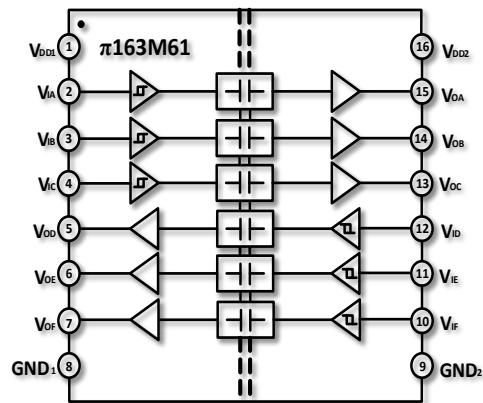
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Standard Digital Isolation	Optocoupler replacement	Interface	Drive	Sampling	Power Drive
1-6 channels standard digital isolation	Digital optocoupler	I <sup>2</sup> C Isolation	Single-channel isolated driver	Isolation amplifier	Ideal diode
Ultra-high withstand voltage standard digital isolation	High-speed optocoupler PTP products	485 Isolation	Dual-channel isolated driver	ADC Isolation	High and low side drivers
Digital isolation with isolated power supply	Optical MOS	CAN Isolation	Non-isolated half-bridge driver	Voltage reference	Integrated GaN power module
	Optocoupler driven	CAN Non-isolated	Intelligent isolated drives		
		With isolated power supply 485/CAN Isolate	Intelligent isolated drive with functional safety		

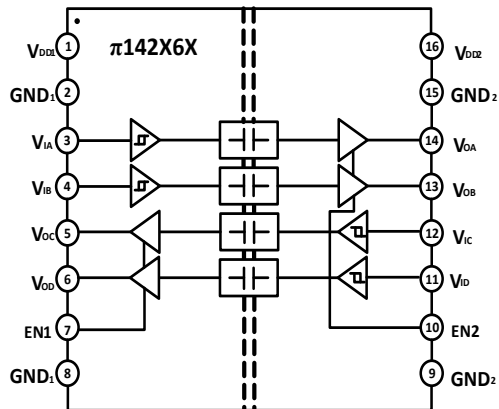
Mass production stage
  Sample stage
  R&D phase
  Conceptual phase



# Standard Digital Isolator



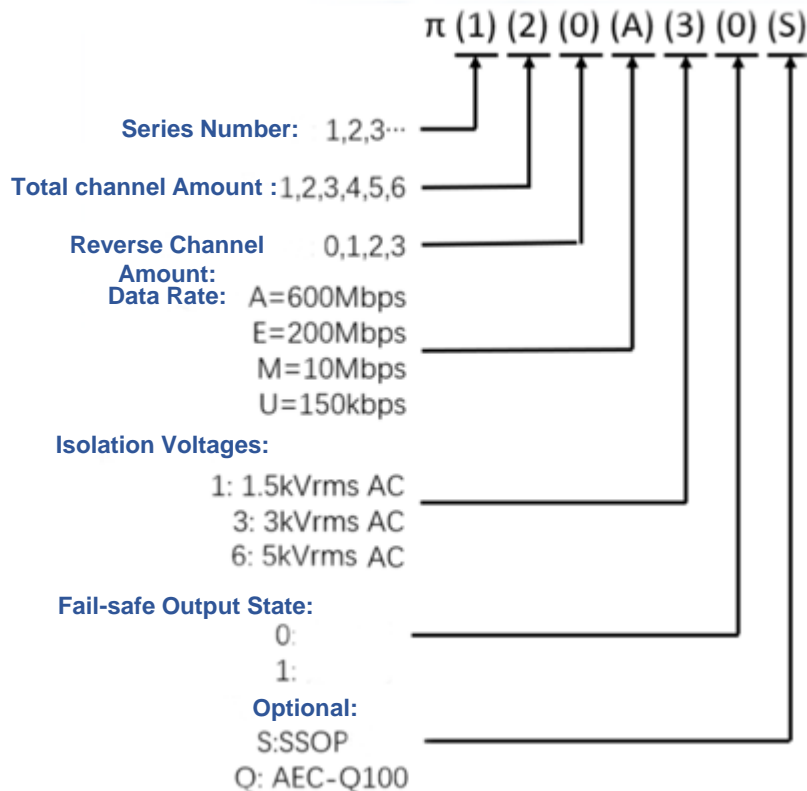
Channel Amount:6



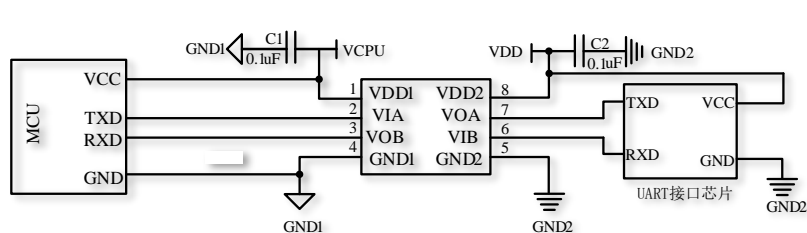
Channel Amount:4

The main parameters	category
Total channel Amount	1,2,3,4,6
Reverse Channel Amount	Reverse Channel Amount: 1~3
Data Rate	A(600Mbps);E(200Mbps);M(10Mbps);U(150Kbps)
Isolation Voltages	1.5KV(1); 3KV(3); 5KVrms(6)
Fail-safe Output State	Logic High(1);Logic Low(0)

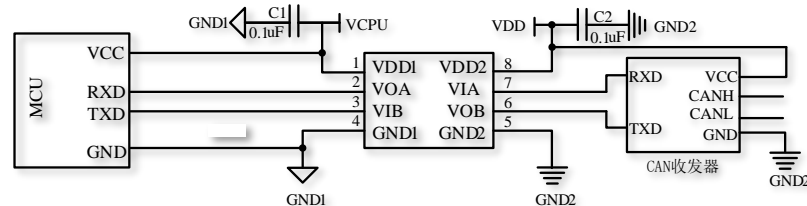
Chips create new value



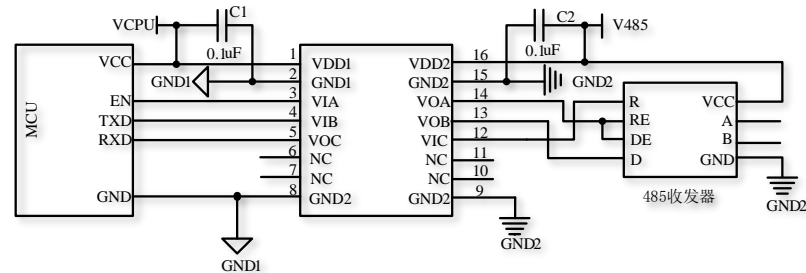
# Standard Digital Isolators Typical Applications



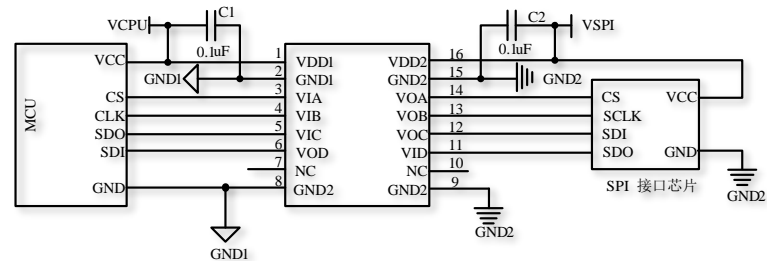
UART/RS232 Communication isolation -  $\pi 122M31/\pi 122M61$



CAN Communication isolation -  $\pi 122M31/\pi 122M61$



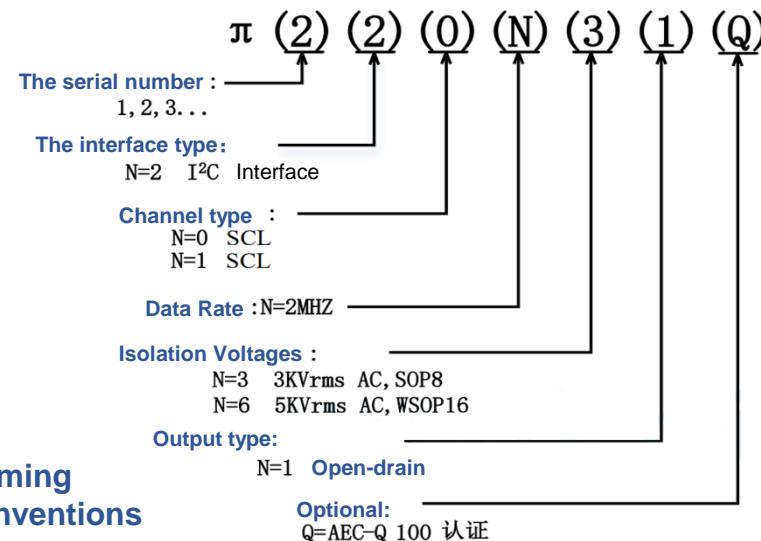
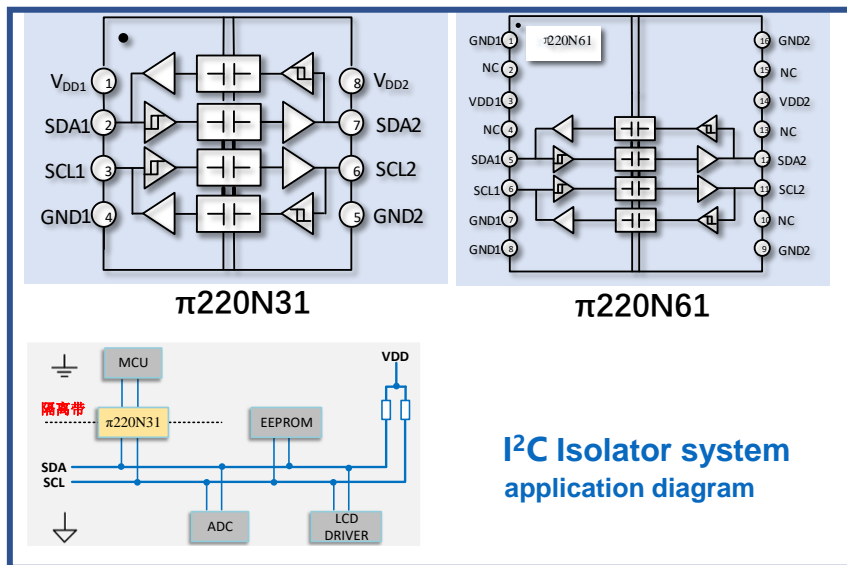
RS485 Communication isolation -  $\pi 131M31/\pi 131M61$



SPI Communication isolation -  $\pi 141M31/\pi 141M61$

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PN.	Max Data Rate	Isolation Voltages ACrms	SDA Channel	SCLChannel	Operating voltage	Operating temperature range	Package	AEC-Q100	Hot Selling Models
$\pi 220N31$	2MHZ	3KV	Bidirectional	Bidirectional	3-5.5V	-40°C~125°C	SOP-8	yes	✓
$\pi 220N61$	2MHZ	5KV	Bidirectional	Bidirectional	3-5.5V	-40°C~125°C	WSOP-16	yes	✓



**Naming  
conventions**

# DFN Encapsulation & Automotive Grade Products

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## AEC-Q100 Automotive-grade digital isolators and key applications



- ✓ Electric drive electronic control
- ✓ BMS
- ✓ OBS
- ✓ In-vehicle DC-DC

- The full range of transmission rates up to 200Mbps
- AEC-Q100 Grade1 certified
- Production line for automotive grade products that meets IATF16949
- Additional quality control in fab, device packaging, and final assembly

## The world's smallest package of digital isolators and key applications



Digital Isolator  
8-P-DFN

- ✓ Secondary power supply
- ✓ 5G communication
- ✓ GaN PD power supply
- ✓ New energy power supply

## PN:

- □ 110x1x
  - □ 120x1 x
  - □ 122x1 x
- Size: 2mm \* 3mm

# Optocoupler-compatible Isolated Product

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Optocoupler-compatible isolator Pai6xxx	product material number 2Pai Part Number	Competitor information Benchmarking Products
Optocoupler compatible isolated drive	Pai8201	Silicon Labs Si8261BBD-C-IS TI UCC23513
Optocoupler Compatible Isolator	Pai85136/7	6N137
Optocoupler compatible with solid-state relays	Pai8558EQ	Broadcom ASSR-601Jx Toshiba TLX9160T



# Optocoupler Compatible Isolated Driver : Pai8201E

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## Features

- Single-channel isolated driver output (5A Peak source current , 5A peak sink current)
- Drive side 13V UVLO, power supply range 15V~25V
- Logic side optocoupler compatible
- WB SO6 package (8mm creepage distance)
- Isolation performance: 5.0kVrms for 1 minute
- CMTI TYP: 100KV/us
- Pulse width distortion is less than 35ns

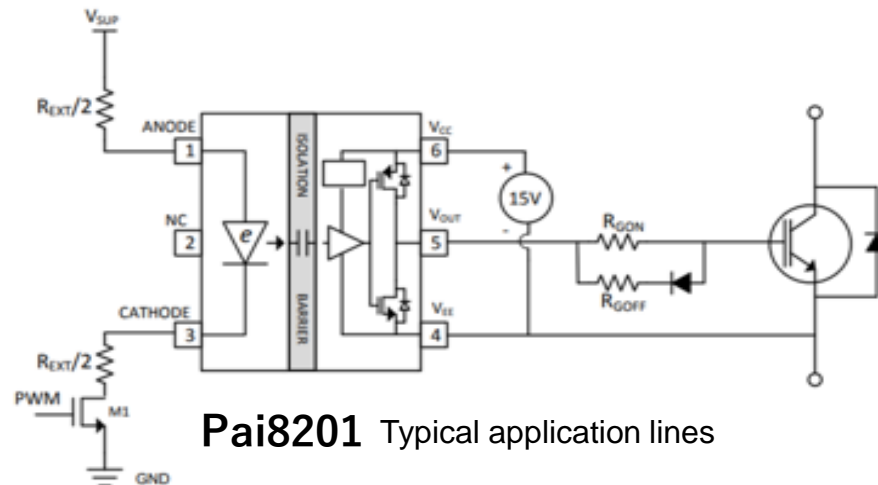
## Benefits

- PIN TO PIN
- Optocoupler Compatible Input
- Drive peak current up to 5A
- Wide body 6-pin package

## Applications

**Samples: Q1, 2023**

- Inverter
- UPS and PSU
- Isolated DCDC power supply
- EV/HEV Power Module



# Optocoupler Compatible Isolator: Pai85136/Pai85137

Chips create new value

## Features

- Pin-compatible with popular high-speed optocouplers
- 4.5V to 30V output supply voltage
- Higher common-mode transient immunity: >50 kV/ $\mu$ s typical
- PCB footprint compatible with optocoupler packaging
- Single/Dual channel diode emulator input
- Data rates dc 1Mbps/10Mbps
- Propagation delay 75 ns
- Operating junction temperature, :  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- Safety-related certifications:
  - 5.0kVRMS isolation for 1 minute per UL 1577

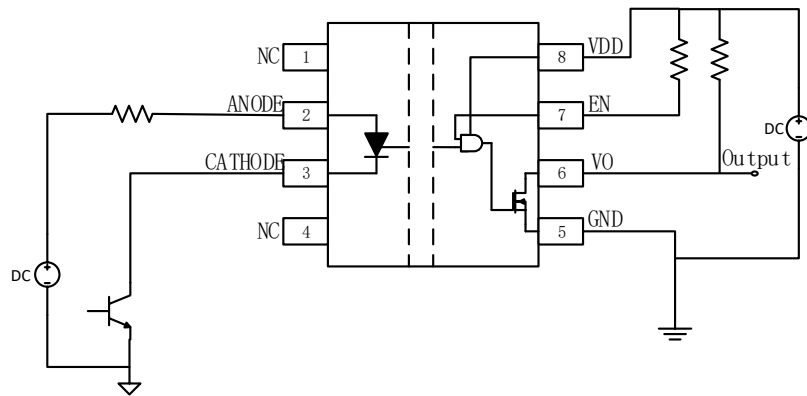
## Benefits

- Pin-compatible, drop in upgrade for popular high-speed digital optocouplers

## Applications

## Samples Available

- Industrial automation
- Motor controls and drives
- Isolated switch mode power supplies
- Isolated data acquisition
- Test and measurement equipment



# Optocoupler Input Compatible 1500V PhotoMos Pai8558E

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## Features

- Diode emulator input compatible with PhotoMOS
- AEC-Q100 grade 1 qualified
- Breakdown voltage: min. 1500V at  $IDSS=100\mu A$
- Avalanche rated bidirectional MOSFETs
- On-resistance,  $R_{DS(ON)} < 300\Omega$  at  $I_{LOAD}=20mA$
- Off-state leakage,  $I_{OFF} < 1\mu A$  at  $V_{DS} = 1500V$ ,  $T_a=25^\circ C$
- Creepage and clearance  $\geq 8\text{ mm}$  (input-output)
- Package: 300 mil SO-12
- Safety and regulatory approvals:
  - 5000 VRMS for 1 minute per UL1577
  - 6250 VPEAK surge voltage per VDE0884-11
- Maximum working insulation voltage 1414 VPEAK

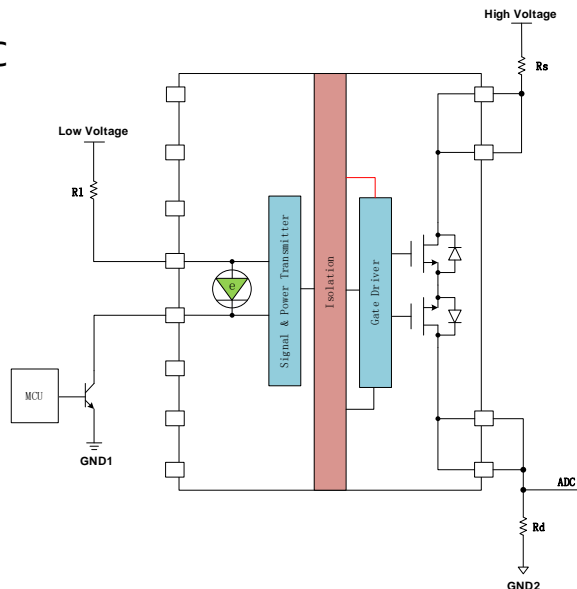
## Benefits

- PhotoMOS replacement without any application circuit change as it is pin-to-pin compatible
- Robust design with high reliability and long life time

## Applications

## Samples Available

- Insulation resistance measurement/leakage detection
- Leakage current blocking switch in series with high voltage measurement resistor ladder



Benchmarking Products

Broadcom: **QCPL-A58JV**

Toshiba: **TLX9160T**

# Sampling

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Sampling Pai5xxx	2Pai Part Number	Benchmarking Products
Current Sense Isolated Amplifier	Pai8300	TI AMC1300B
Current Sense Isolated Amplifier	Pai8311	TI AMC1311
Voltage Reference	Paixxxx	TI REF50xx

# Current Sensing Isolated Amplifiers: Pai8300

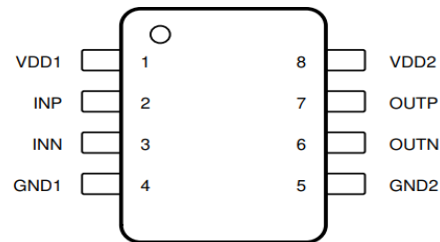
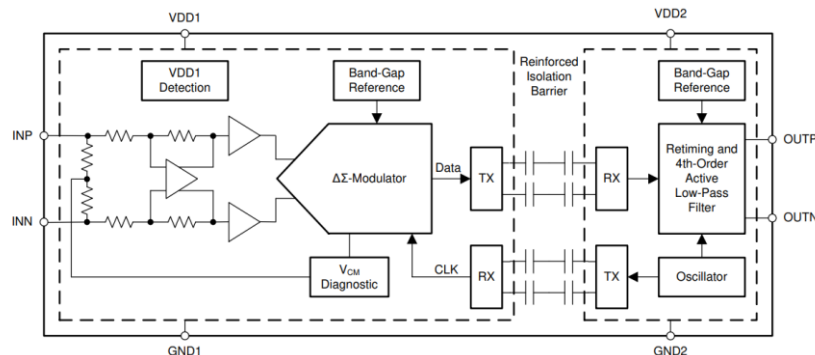
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## Feature

- $\pm 250$ -mV input voltage range optimized for current measurement using shunt resistors
- Low offset error and drift:  $\pm 0.2$  mV (max),  $\pm 3$   $\mu\text{V}/^\circ\text{C}$  (max)
- Fixed gain: 8.2
- Very low gain error and drift:  $\pm 0.3\%$  (max),  $\pm 50$  ppm/ $^\circ\text{C}$  (max)
- Low nonlinearity and drift: 0.03%, 1 ppm/ $^\circ\text{C}$  (typ)
- 3.3-V operation on high-side
- Safety-related certifications:
  - 7071-VPK reinforced isolation per DIN VDE V 0884-11: 2017-01
  - 5000-VRMS isolation for 1 minute per UL1577
  - High CMTI : 140 kV/ $\mu\text{s}$  (MIN)

## Function Diagram and Package

**Sample: Sept, 2022**



WB SOIC-8



# High Precision Voltage Reference

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## Features

- Qualified for Automotive Applications
- Low Temperature Drift
  - ✓ Excellent Grade: 3 ppm/°C(max)
  - ✓ Standard Grade: 8 ppm/°C(max)
- High Accuracy
  - ✓ Excellent Grade: 0.05% (max)
  - ✓ Standard Grade: 0.1% (max)
- Low Noise: 3 uVpp/V
- Excellent Long-Term Stability
  - ✓ 5 ppm/1000 hr (typ) after 1000 hours
- High Output Current:  $\pm 10$  mA
- Temperature Range:  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$

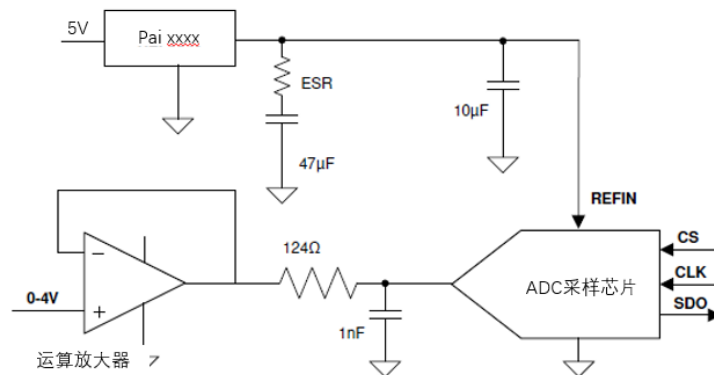
## Benefits

- Pin-to-Pin compatible with mainstream products in the market
- Replacement can be performed without any application circuit change

## Applications

In Concept

- High Resolution Data Acquisition Systems
- Precision Instrumentation
- Industrial Process Control
- Optical Control Systems



## Benchmarking Products

TI	REF50xx
Maxim	MAX607x

Drivers Pai8xxx	2Pai Part Number	Benchmarking Products
Single Channel Isolated Gate Driver	<a href="#">Pai8211A</a> Pai8211C	TI <a href="#">UCC5350SB</a>
Dual Channel Isolated Gate Driver	Pai823XX	Silicon Labs <a href="#">Si8233</a> TI <a href="#">UCC21520</a>
Optocoupler Compatible Isolated Gate Driver	Pai8201E	Silicon Labs <a href="#">Si8261BBD-C-IS</a> TI <a href="#">UCC23513</a>
High Voltage Half Bridge Gate Driver	Pai8131A Pai8171A	IR <a href="#">IR2103(S)</a> <a href="#">IR2104S</a>
Intelligent Isolated Gate Driver	Pai6861C	Toshiba <a href="#">TLP5214A</a> Broadcom <a href="#">ACPL-333J</a>
	<a href="#">Pai8361AQ</a>	TI <a href="#">UCC21750Q</a>

# Single-channel isolated driver: Pai8211A

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## Features

- Single-channel isolated driver output (6A Peak source current , 6A peak sink current)
- Drive side 8V UVLO, power supply range 9.5V~33V  
Logic side power supply range 2.5V~5.5V
- NB SOIC-8 package (4mm creepage distance)
- WB SOIC-8 package (8mm creepage distance)
- Isolation performance: 3.75kVrms or 5kVrms for 1 minute
- CMTI TYP: 150KV/us
- Pulse width distortion less than 10ns

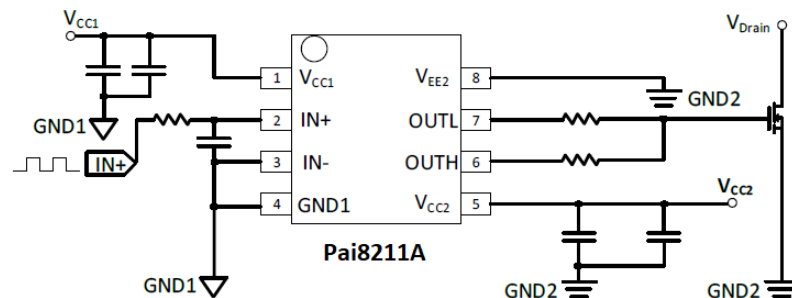
## Benefits

- PIN TO PIN
- Separate output, flexible EMI debugging
- CMOS input, support 2.5V power supply
- Drive peak current up to 10A, power supply supports 33V
- Isolation withstand voltage up to 3.75kVrms or 5kVrms

## Applications

- Inverter
- UPS and PSU
- Isolated DCDC power supply
- EV/HEV Power Module

**Available**



# Single-channel isolated driver: Pai8211C

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## Features

- Single-channel isolated driver output (6A Peak source current , 6A peak sink current)
- Drive side 12V UVLO, power supply range 13V~33V
- Logic side power supply range 2.5V~5.5V
- NB SOIC-8 package (4mm creepage distance)
- WB SOIC-8 package (8mm creepage distance)
- Isolation performance: 3.75kVrms or 5kVrms for 1 minute
- CMTI TYP: 150KV/us
- Pulse width distortion less than 10ns

## Benefits

- PIN TO PIN
- With Miller Clamp Protection
- CMOS input, support 2.5V power supply
- Drive peak current up to 10A, power supply supports 33V
- Isolation withstand voltage up to 3.75kVrms or 5kVrms

## Applications

**Available**

- switching power supply
- UPS and PSU
- Solar inverters
- EV/HEV Power Module

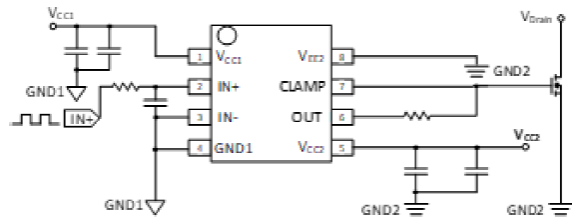


Figure22A. typical application circuit-IN+ Input

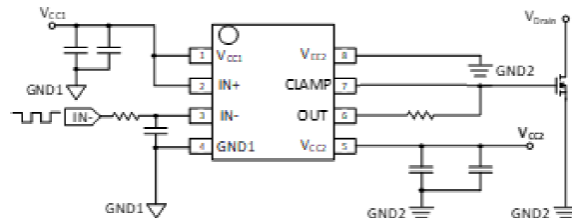


Figure22B. typical application circuit-IN- Input

# Dual isolated driver: Pai823xx

Chips create new value

## Features

- Dual isolated drive outputs (4A Peak source current , 8A peak sink current)
- Drive side UVLO 6V, 9V, 13V optional, power supply range 9.5V~25V
- WB SOIC-14 Wide Body Package (Original and Secondary Creepage Distance 8mm)
- NB SOIC-16 package (primary and secondary creepage distance 4mm)
- Isolation: 5.0kVrms or 3kVrms, 8KV surge
- CMTI: >100KV/us
- Pulse width distortion is less than 5ns

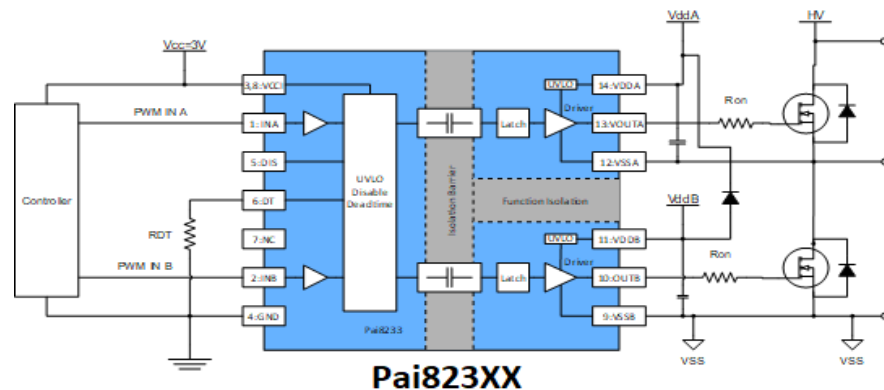
## Benefits

- PIN TO PIN
- 6V, 9V, 13V UVLO optional
- TTL input
- Drive peak current up to 5A
- Dead time adjustable

## Applications

- Motor Control System
- Isolated DCDC power supply
- PV inverter
- Inverter

**Available**



Typical application circuit

# Intelligent isolated driver: Pai8265AQ

Chips create new value

## Features

- $\pm 10\text{A}$  maximum peak output current
- 4A active Miller Clamp.
- Desaturation Detection
- Under Voltage Lock-Out Protection (UVLO) with Hysteresis
- Open Collector Isolated fault feedback
- “Soft” Turn-off
- Automatic Fault Reset after fixed mute time , typical 26us
- High CMTI >100KV/us
- Safety and regulatory approvals:
  - 5700 VRMS for 1 minute per UL1577
  - 6250 VPEAK surge voltage per VDE0884-11
  - Maximum working insulation voltage 2121 VPEAK

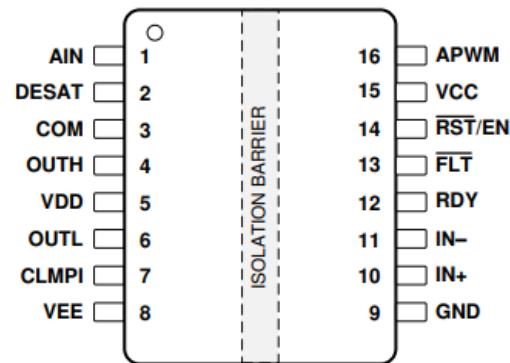
## Benefits

- Pin-to-Pin compatible with mainstream products in the market
- Replacement can be performed without any application circuit change

## Applications

**Sample: Q1, 2023**

- Isolated IGBT/Power MOSFET gate drive
- AC and brushless DC motor drives
- Solar Inverters
- HEV and EV Power Modules



Pin Configuration

**Benchmarking  
Products**

TI

UCC21750

# Smart High Side Driver

Chips create new value

## Features

- Quad channel smart high-side driver with MultiSense analog feedback
- Very low standby current
- Compatible with 3 V and 5 V CMOS outputs
- Multiplexed analog feedback of: load current with high precision proportional current mirror
- Undervoltage shutdown
- Overvoltage clamp
- Load current limitation
- Self limiting of fast thermal transients
- Configurable latch-off on overtemperature or power limitation with dedicated fault reset pin

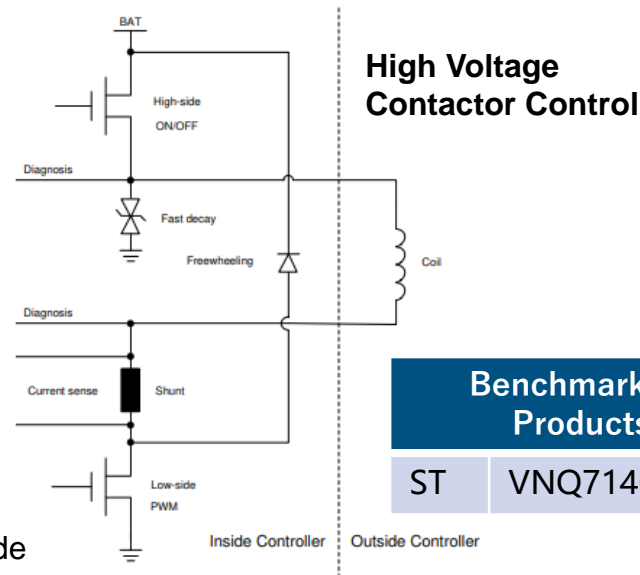
## Benefits

- Pin-to-Pin compatible with mainstream products in the market
- Meets automotive ISO7637 transient requirements without TVS Diode

## Applications

**Sample: Q2, 2023**

- All types of automotive resistive, inductive and capacitive loads
- Specially intended for automotive signal lamps (up to R10W or LED Rear Combinations)





# Ideal Diode Controller

Chips create new value

## Features

- AEC-Q100 qualified with the following results
  - Device temperature grade 1:  
40°C to +125°C ambient operating temperature range
  - Device HBM ESD classification level 2
  - Device CDM ESD classification level C4B
- 3.2 V to 65 V input range (3.9-V start up)
- -40 V reverse voltage rating
- 5-μA shutdown current (EN=Low)
- 80-μA (With Cap)/200-μA (Without Cap) quiescent current
- Charge pump for external N-Channel MOSFET
- Available in 6-pin, 8-pin SOT-23 Package 2.90mm × 1.60 mm; 8-TDFN Package 2mm x 3mm

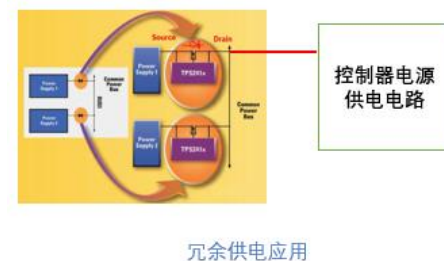
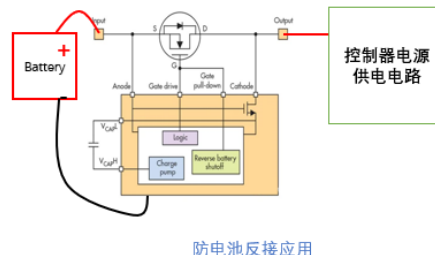
## Benefits

- Pin-to-Pin compatible with mainstream products in the market
- Meets automotive ISO7637 transient requirements without TVS Diode

## Applications

- Active ORing for redundant power
- Automotive ADAS systems – camera
- Enterprise power supplies
- Automotive infotainment systems

**Sample: Q1, 2023**



## Benchmarking Products

TI	LM7470x
ADI	MAX16171

# Isolated interface

Chips create new value

Isolated interface: Pai8xxx	2Pai Part Number	Benchmarking Products
Isolated RS-485 Transceiver	Pai8485 (half duplex) Pai8486 (full duplex)	TI ISO1412 TI ISO1432
Isolated CAN Transceiver	Pai8450	TI ISO1050(TI)

# Pai8485-W1R&Pai8486-W1R –Isolated 485

Chips create new value

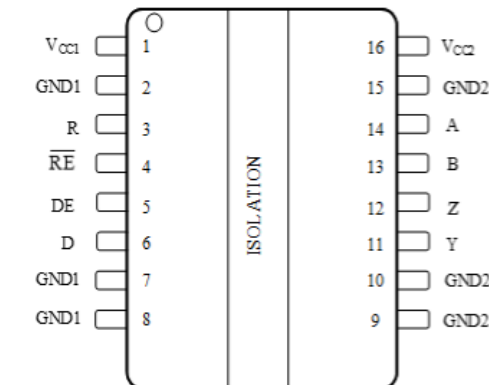
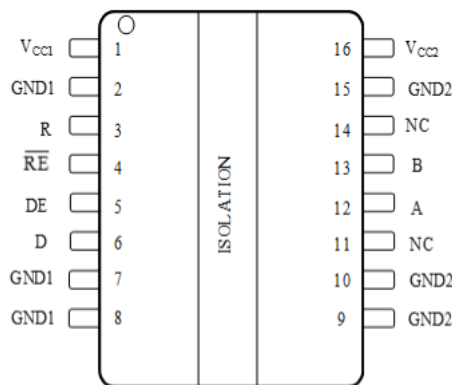
## Features

- Up to 5000Vrms Insulation voltage.
- VDD1 supply voltage: 2.5V to 5.5V.
- Bus side power supply voltage: 4.5V to 5.5V.
- Low-EMI 500-kbps Data Rate for Pai2485.
- 16Mbps Data Rate for Pai2486.
- High CMTI: +100kV/us.
- High system level EMC performance:
  - Bus Pins meet IEC61000-4-2 t10kV ESD.
- Fail-safe protection receiver.
- 1/8 Unit load up to 256 nodes on bus.
- Operation temperature: -40C ~ 105C.
- RoHS-compliant, Wide-body SOIC-16 package.
- Pin compatible to most isolated RS - 485 transceivers.
- Safety-related certifications: (Pending).

## Functional Block Diagram

**Sampling: Oct, 2022**

- Factory Automation & Control
- Isolated RS-485 communication
- Smart electric meter and water meter
- Security and protection monitoring



**Benchmarking  
Products**

ISO1412

ISO3082

# Pai8450-Isolated CAN

## Features

- Up to 5000Vrms Insulation voltage
- VDD1 supply voltage: 3.0V to 5.5V
- Bus side power supply voltage: 4.5V to 5.5V
- 16Mbps Data Rate
- High CMTI:  $\pm 100\text{kV/us}$
- Up to 110 transceivers on the bus
- Driver (TXD) Dominant Time- out Function Bus- Fault Protection of -27 V to 40 V
- Operation temperature: -40°C ~125°C RoHS- compliant packages: WB SOIC16

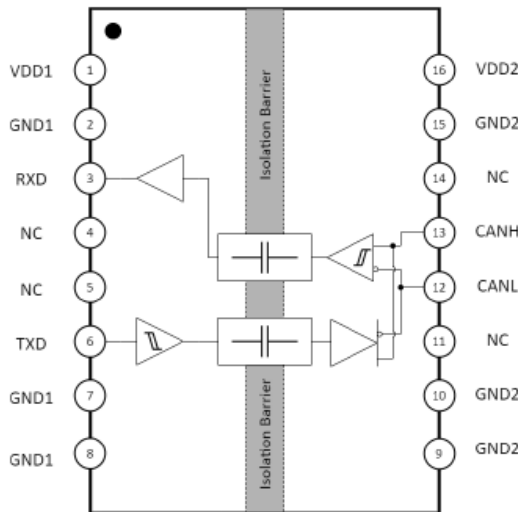
## Benefits

- Highly integrated isolated Transceiver
- Supports 3.3V and 5V Microprocessors

Chips create new value

## Functional Block Diagram

**Sampling: Oct, 2022**



**Benchmarking  
Products**

ISO1050

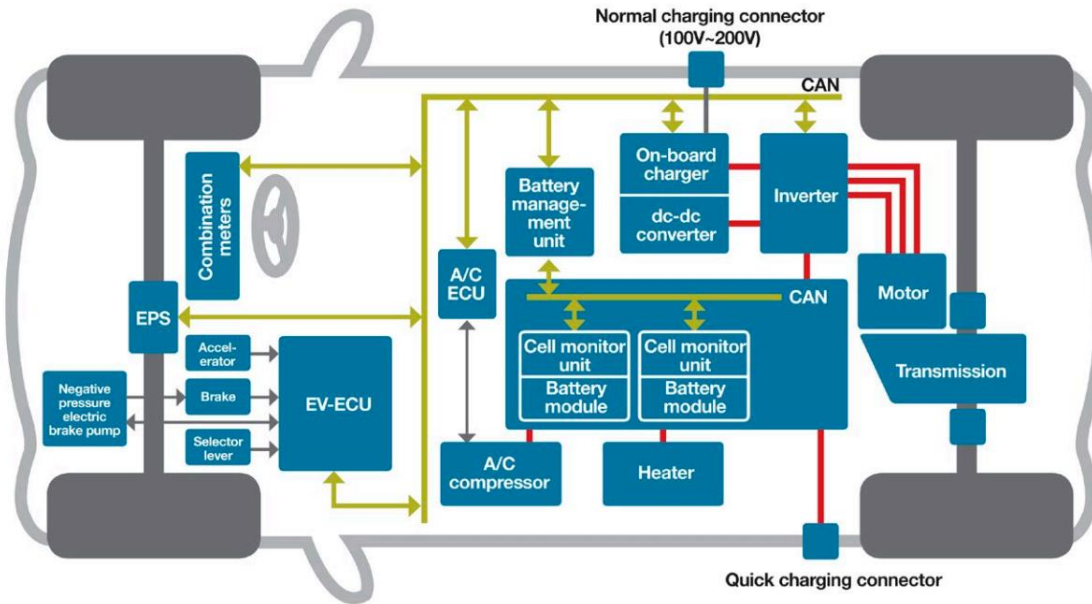


# PRODUCT APPLICATION SCENARIOS

# Application Scenarios

Chips create new value





## Key Applications

## OBC/DC-DC

- OBC(On-Board Charger)
- DC-DC Converter, Convert high (200~800V) voltage to low voltage

## BMS(Battery Management System)

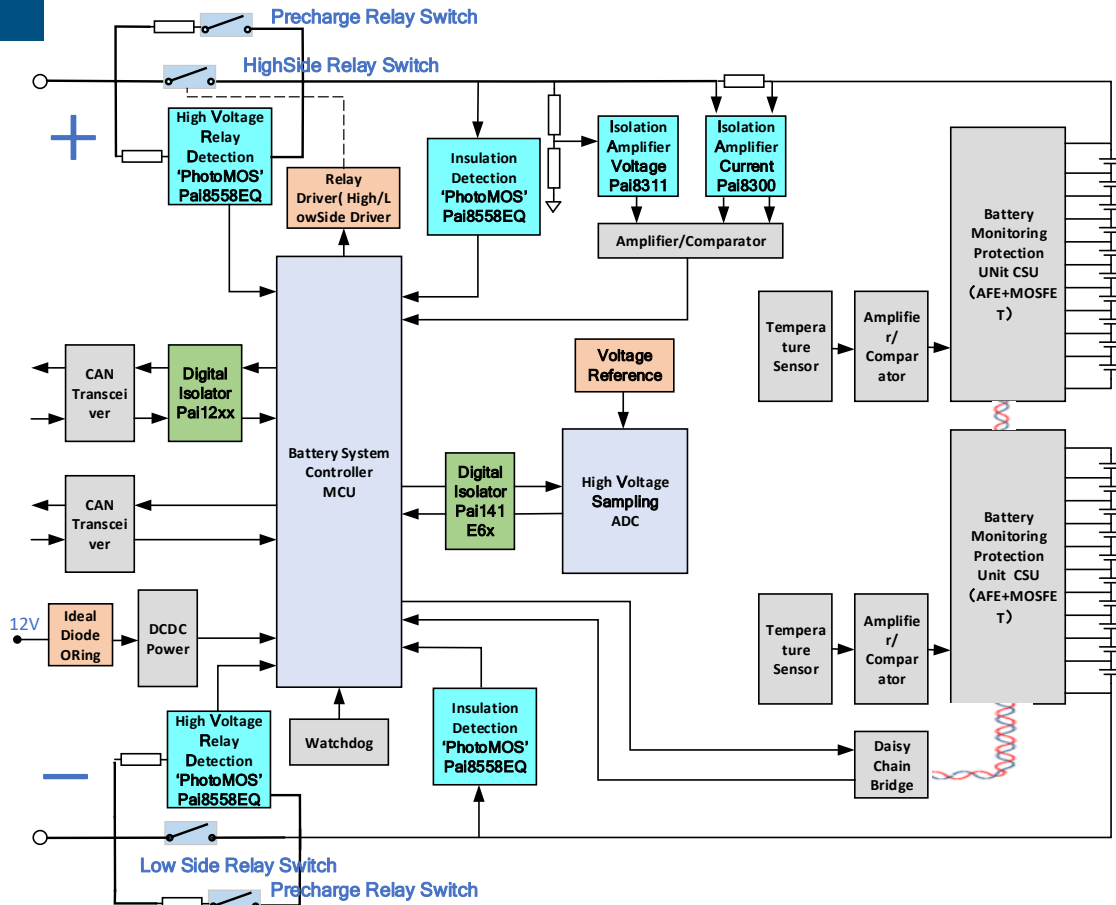
- BMS Monitor and manage battery cells

## Inverter(motor driver)

## Air conditioners and Heaters(thermal management)



## Main Products in BMS



Chips create new value

SPI Communication Isolation-  
Digital Isolator: Pai141E60Q/  
Pai141E61Q (Compatible With TI  
ISO774x/F)

BMS Insulation detection:  
Pai8558EQ (Compatible With  
QCPL-A58J, TLX9160T)

Current Sampling: Pai8300  
(Compatible With TI-AMC1301/  
AMC1300)

Voltage Sensing: Pai8311 (Compatible  
With TI-AMC1311)

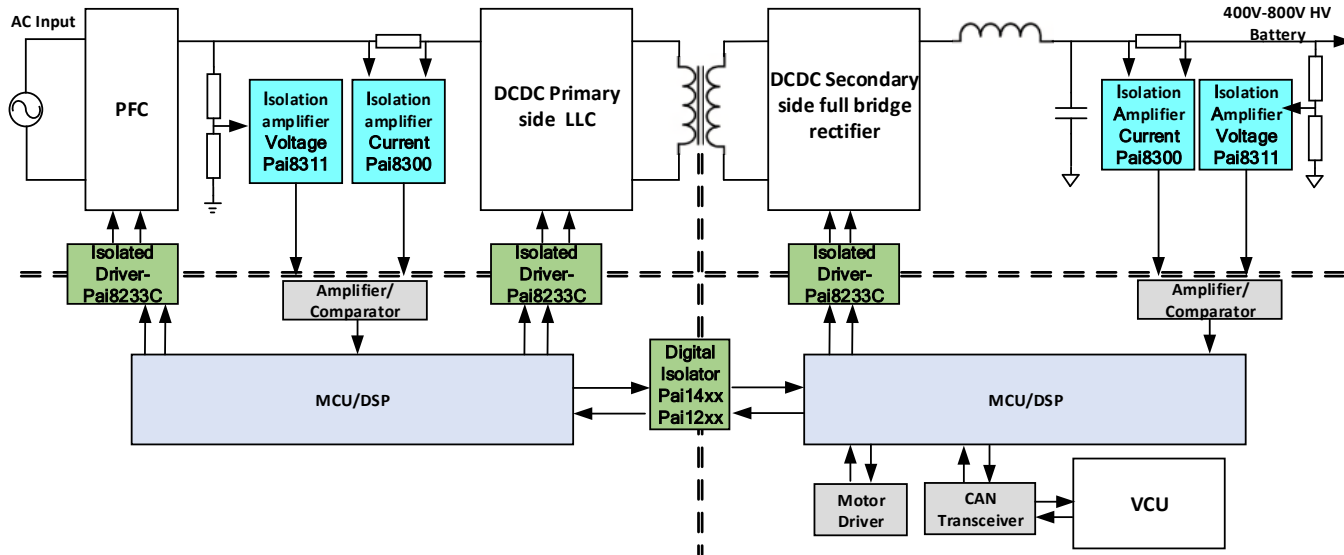
Redundant Power Supply: ideal  
diode(Compatible With TI-LM7470x,  
ADI-MAX16171)

Relay driver(Compatible With ST-  
VNQ7140, VNQ7050)

High Precision ADC Sampling: High  
Precision Voltage Reference (Compatible  
With TI-REF50xx)

# Electric Vehicle Applications - OBC

Chips create new value

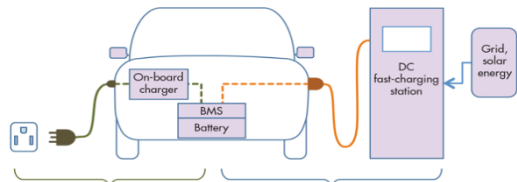


Driver Signal Isolation -  
Pai8233CQ , (Compatible  
With: TI-UCC21520, Silabs-  
Si8233)

Communication Isolation -  
Pai14xx/12xxQ ,  
(Compatible With TI-  
ISO774x/772x)

Current Sensing: Pai8300  
(Compatible With TI-  
AMC1301/AMC1300)

Voltage Sensing: Pai8311  
(Compatible With TI-  
AMC1311)

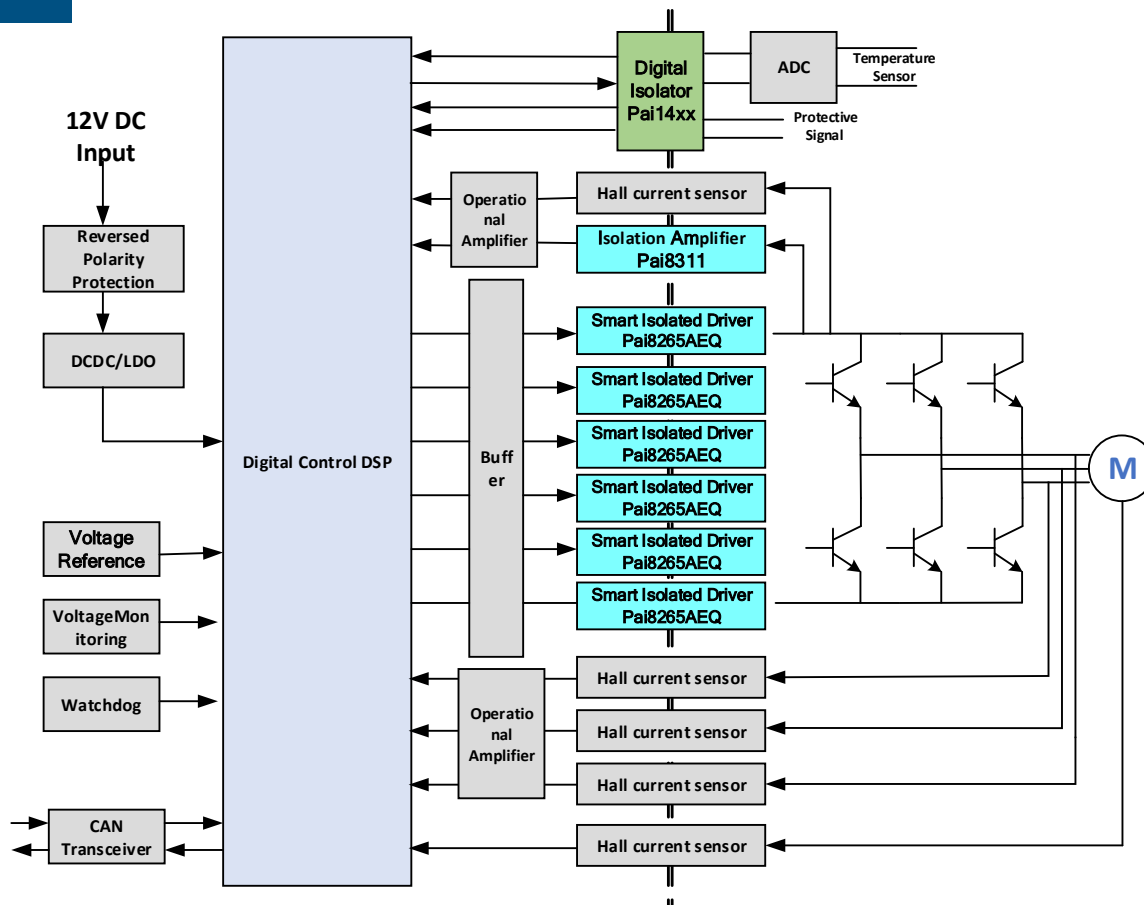


- AC charging
- Every vehicle has an on-board charger.
  - Limited power, slow charging.

- DC charging
- Infrastructure investment is shared among hundreds of users.
  - Large power rating, fast charging.
  - Capable of integration with renewable resources.

# Electric Vehicle Applications – Inverter

Chips create new value



Communication Isolation : Pai14xx  
(Compatible With: TI-ISO774x)

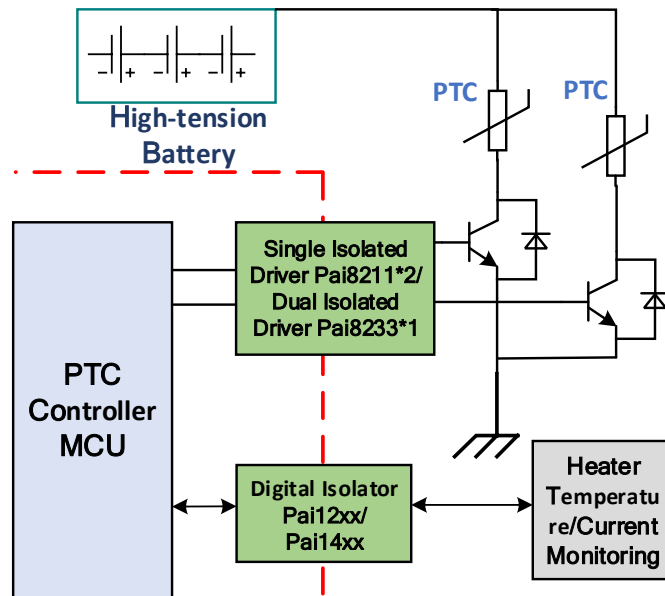
IGBT Driver Signal Isolation: Pai8265AEQ  
(Compatible With: TI-UCC21750)

Bus Voltage Sampling: Isolated  
Amplifier: Pai8311Q (Compatible With:  
TI-AMC1311)

# Electric Vehicle Applications - Air Conditioning & Heaters

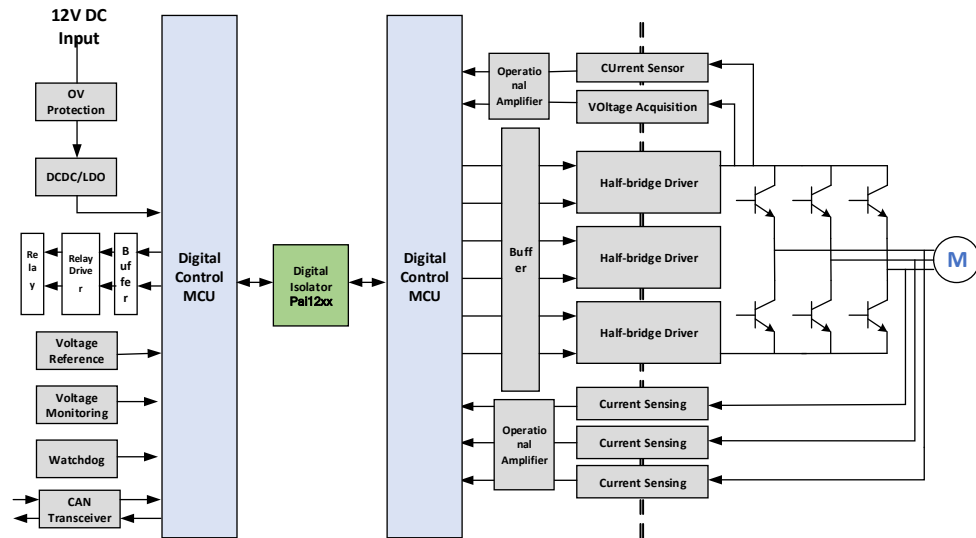
Chips create new value

## PTC Heater



- Communication Isolation : Pai12xx/14xx (Compatible With: TI-ISO774x/772x)
- IGBT Driver Signal Isolation: Pai8211\*2(Compatible With: TI-UCC5350). Pai8233\*1(Compatible With: TI-UCC21520)

## Air conditioner compressor controller



- IGBT Driver Signal Isolation: Pai8233\*3 (Compatible With: TI-UCC21520). Or: Pai12xx\*3+ Non-isolated Driver.
- Current & Voltage Sampling: Pai8300/Pai8311.

## Typical Cooperative Customers of New Energy Vehicles

Chips create new value

**CATL**  
宁德时代

 小鹏

  
LEAPMOTOR  
零跑汽车

**DESAY** 蓝微电子

 哈啰出行

**BYD**

 蔚来

  
AITO

**BMser** 协能科技  
TECHNOLOGY

 嘉佰达科技

 上汽集团  
SAIC MOTOR

 理想

**SUNWODA**  
欣旺达


 NEBULA

 星恒

  
广汽集团  
GAC GROUP

 长安汽车  
CHANGAN AUTO

**Welling**

 Segway-Ninebot  
九号机器人

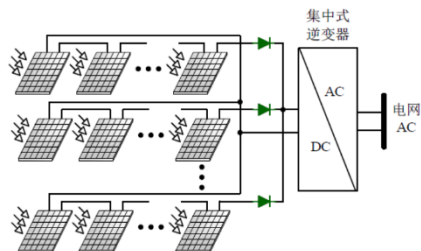
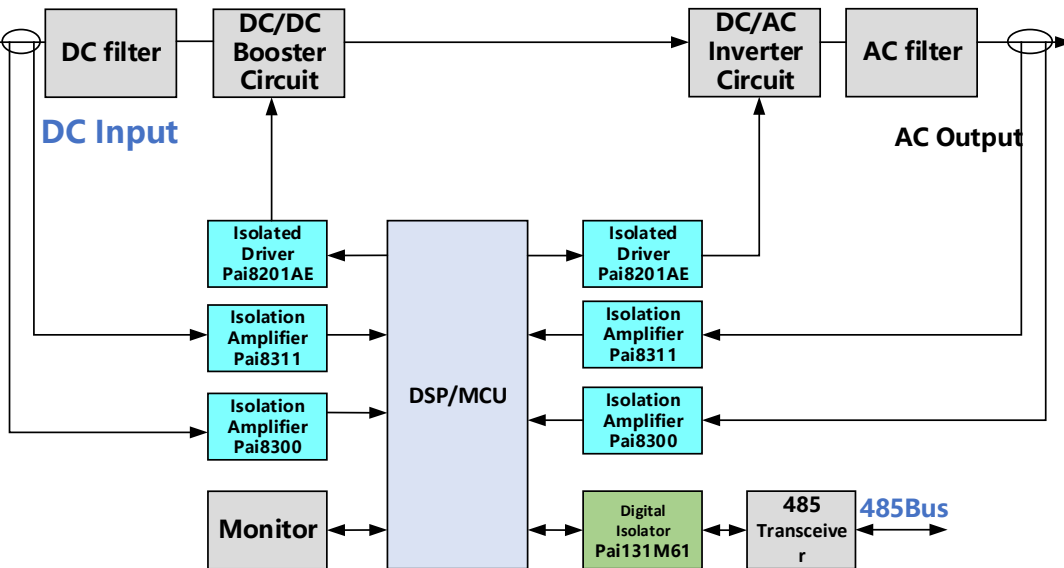
 飞毛腿  
SCUD

# Photovoltaic Inverter

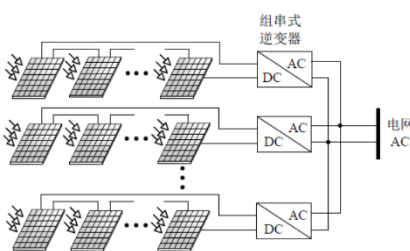
Chips create new value



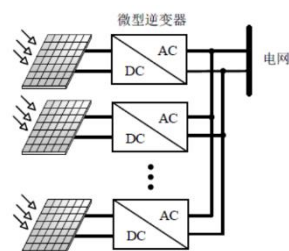
Photovoltaic (pv) panel



Centralization inverter



String inverter



Micro inverter



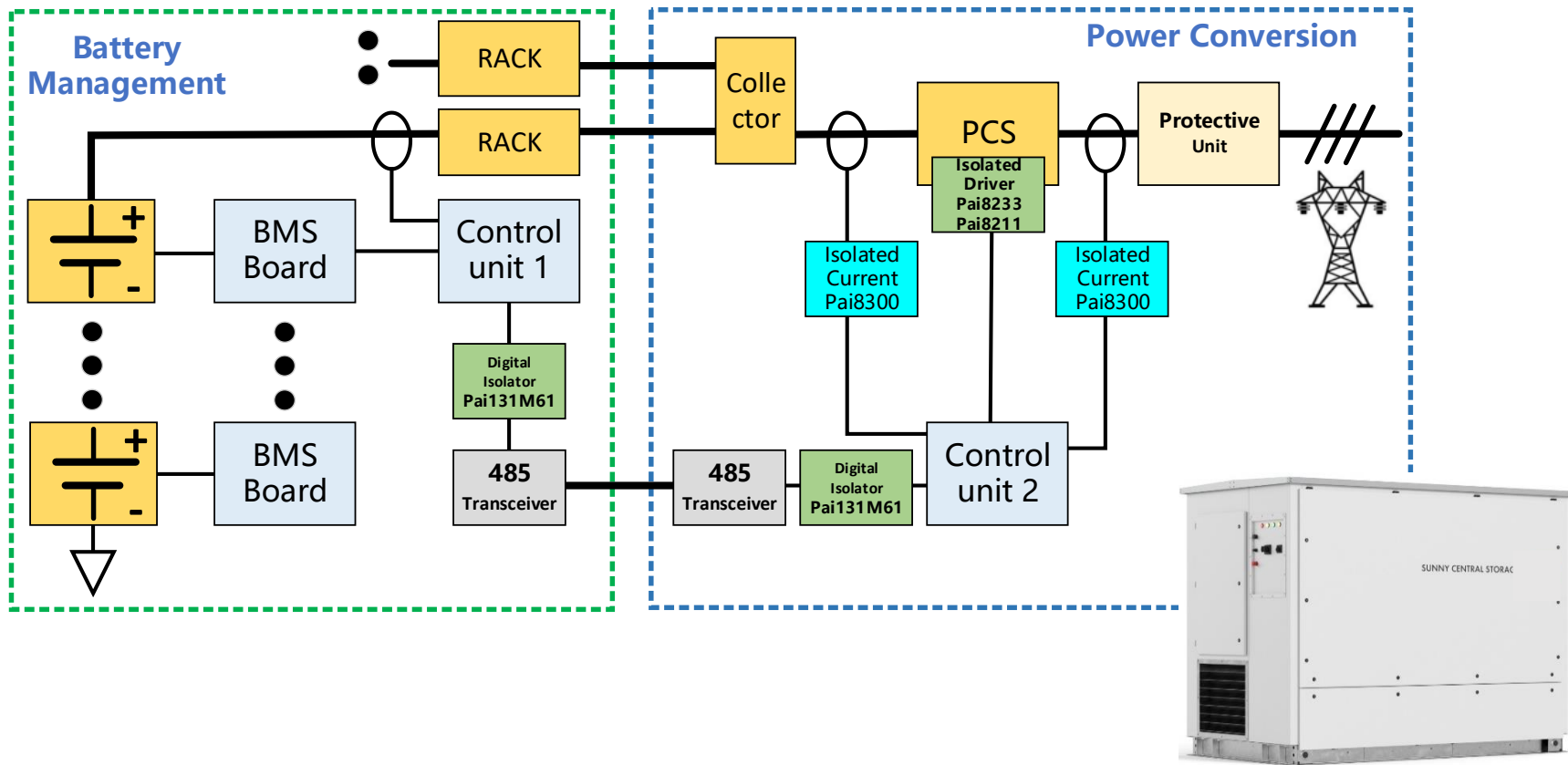
Centralized inverter

String inverter

Micro inverter

# Centralized Energy Storage

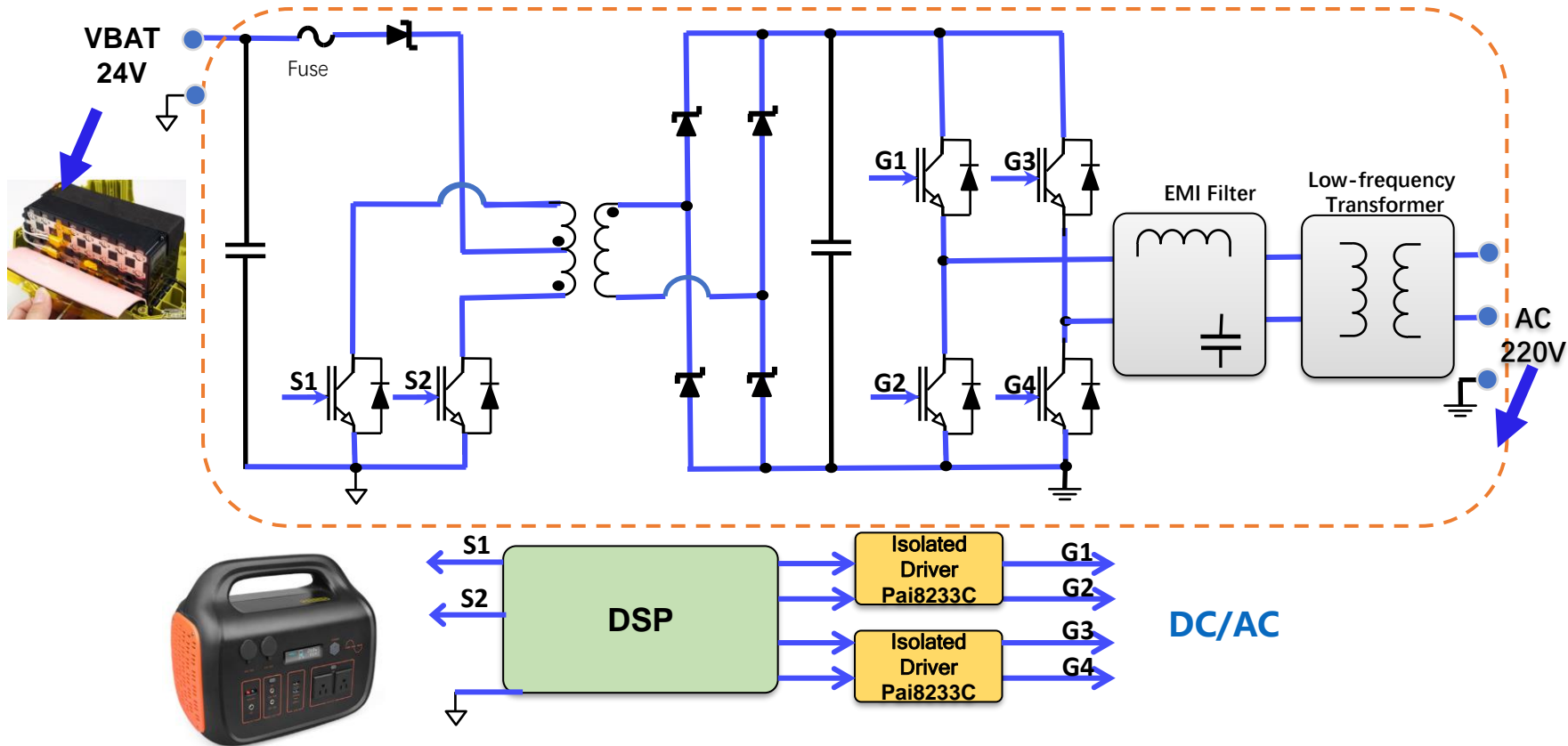
Chips create new value





# Portable Energy Storage Products

Chips create new value



# Power Supply: AC/DC、DC/DC

Chips create new value

## Successful Cases



## Commonly Used Models

PI120M30

PI122M30

PI220N31

PI122M61

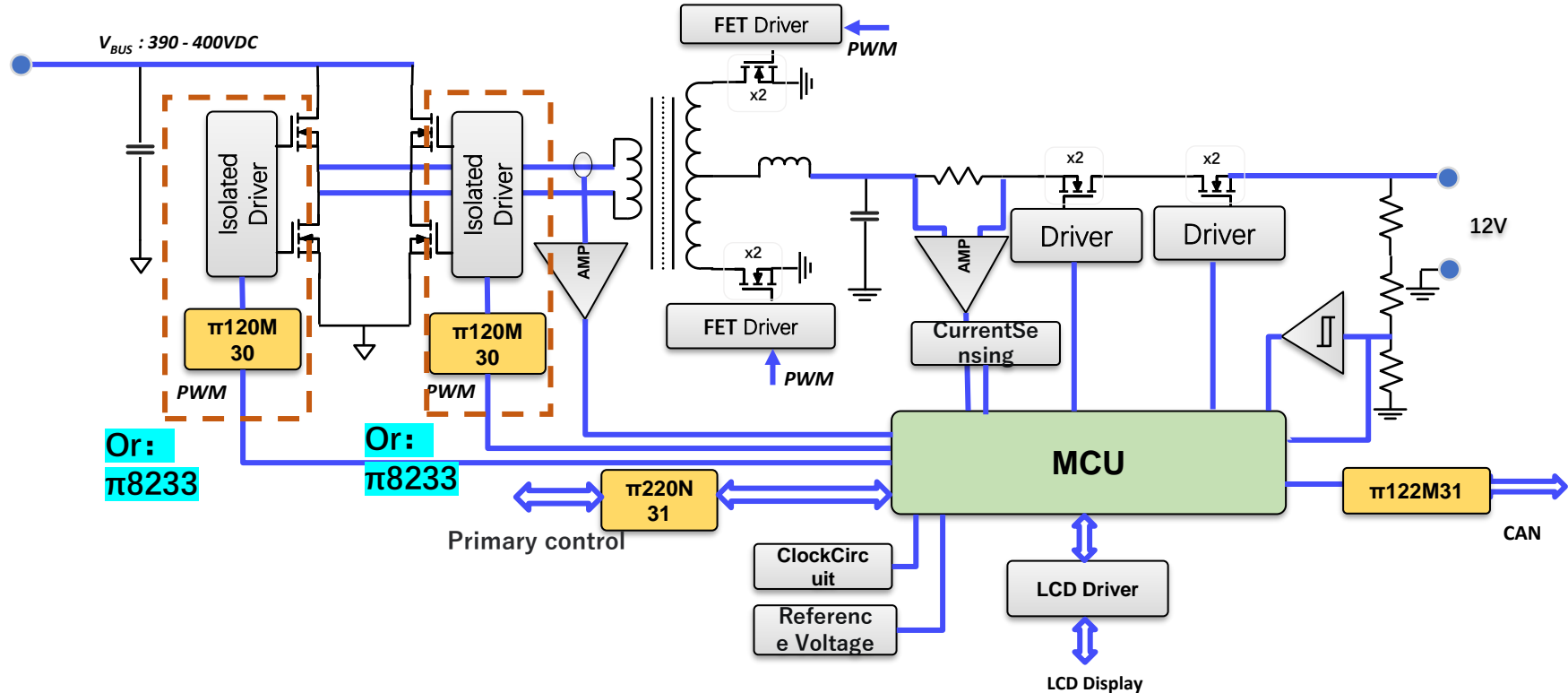
Compatible models:

SI8641BD, SI8622, SI8600, ISO7720, ISO1540, 6N137



# Power Supply: Isolated Phase Shifted Full Bridge DC/DC Convertor

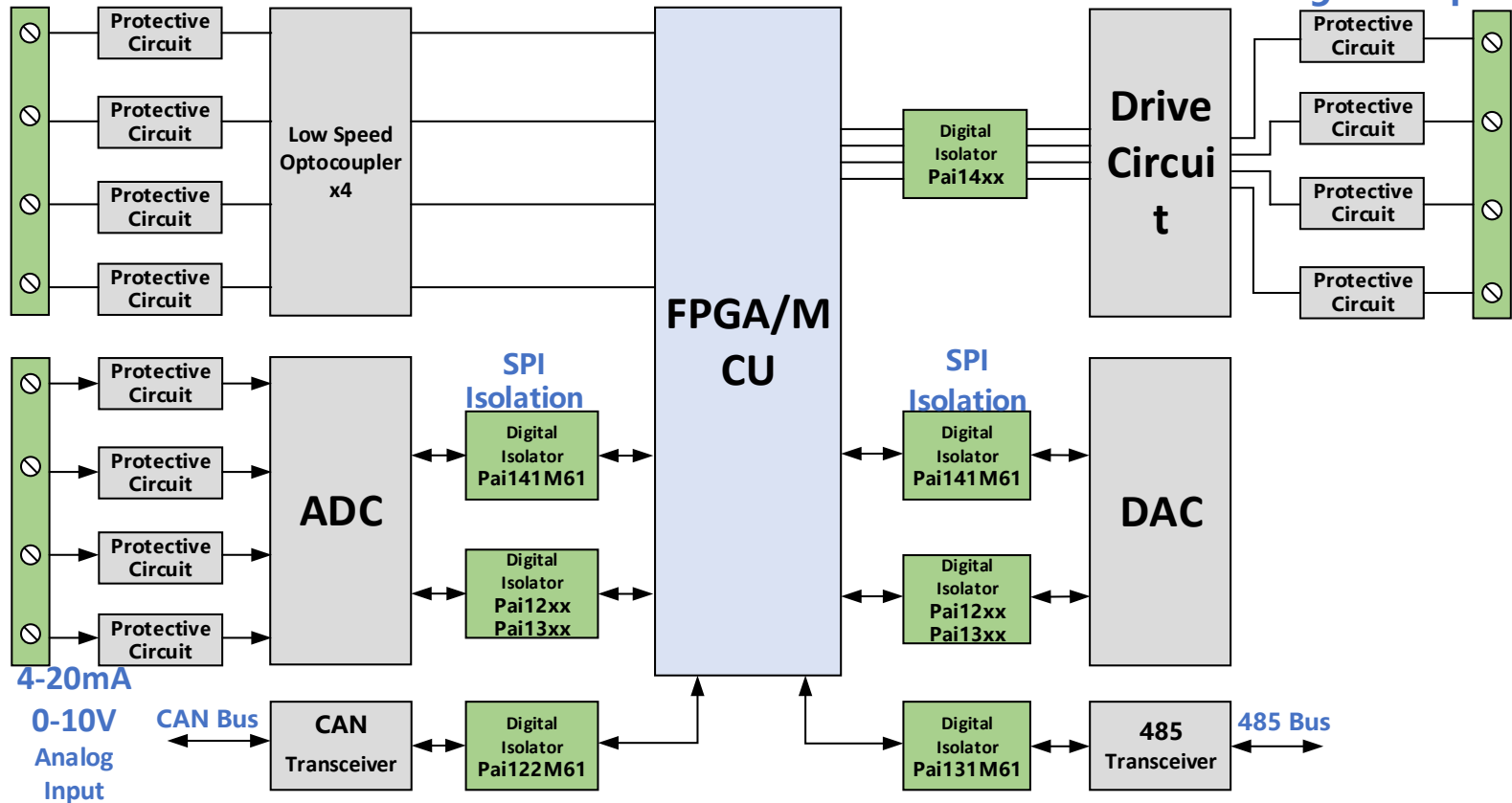
Chips create new value



# Industrial Control: PLC

Chips create new value

## Digital Input



# Industrial Control: Servo Motor Controller

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## Successful Cases



Door  
Motor  
Controller



## Recommended Model:

Pai160M60

Pai122M31

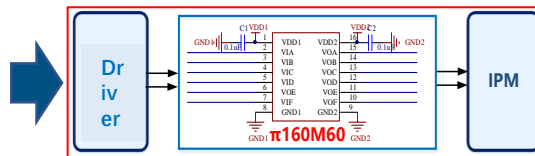
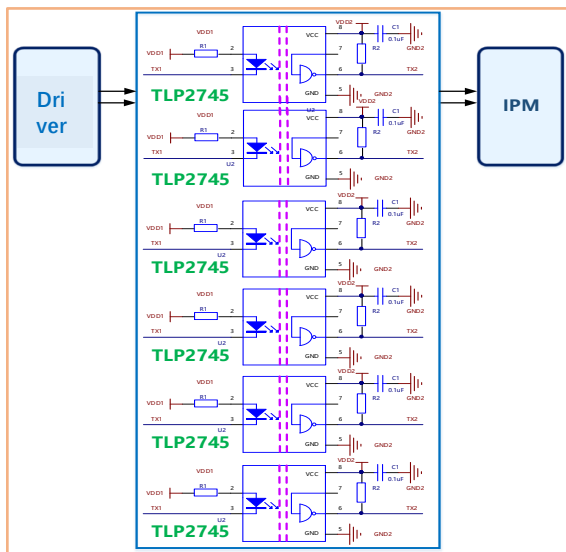
Pai131M31

Pai160M30

# Industrial Control: Servo Motor Controller

Chips create new value

Item	Transmission Rate(PWD<10ns)	Transmission Delay	Power Consumption	Working Temperature	CMTI	PCB Area
TLP2745*6	2Mbps	40ns	10mA*6	-40°C~85°C	25kV/us	1000mm <sup>2</sup>
π160M60	25Mbps	11ns	3mA	-40°C~125°C	120kV/us	190mm <sup>2</sup>

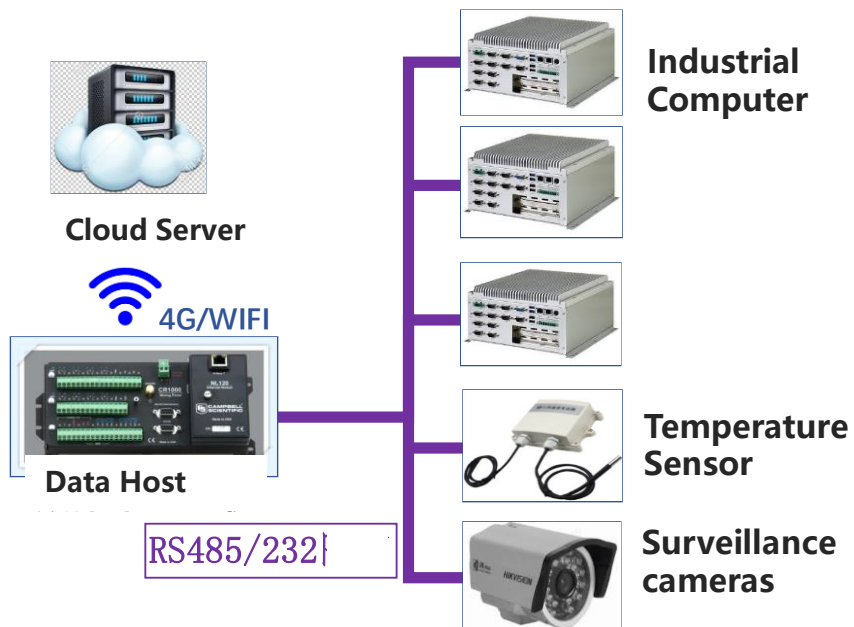


## USE: Driver Signal Isolation

TLP2745 Design			π160M60 Design		
Item	Qty	Price (¥)	Item	Qty	Price (¥)
TLP2745	6	12	π160 M60	1	<8
Cap 0.1uF	6	0.3	Cap 0.1uF	2	0.05
Resistance	12	0.1			
SMT Fee		0.4	SMT Fee		0.12
<b>Total:</b>	<b>24</b>	<b>12.8(¥)</b>		<b>3</b>	<b>&lt;8.17 (¥)</b>

# Industrial Control: Data Collection System

Chips create new value



## Successful Case



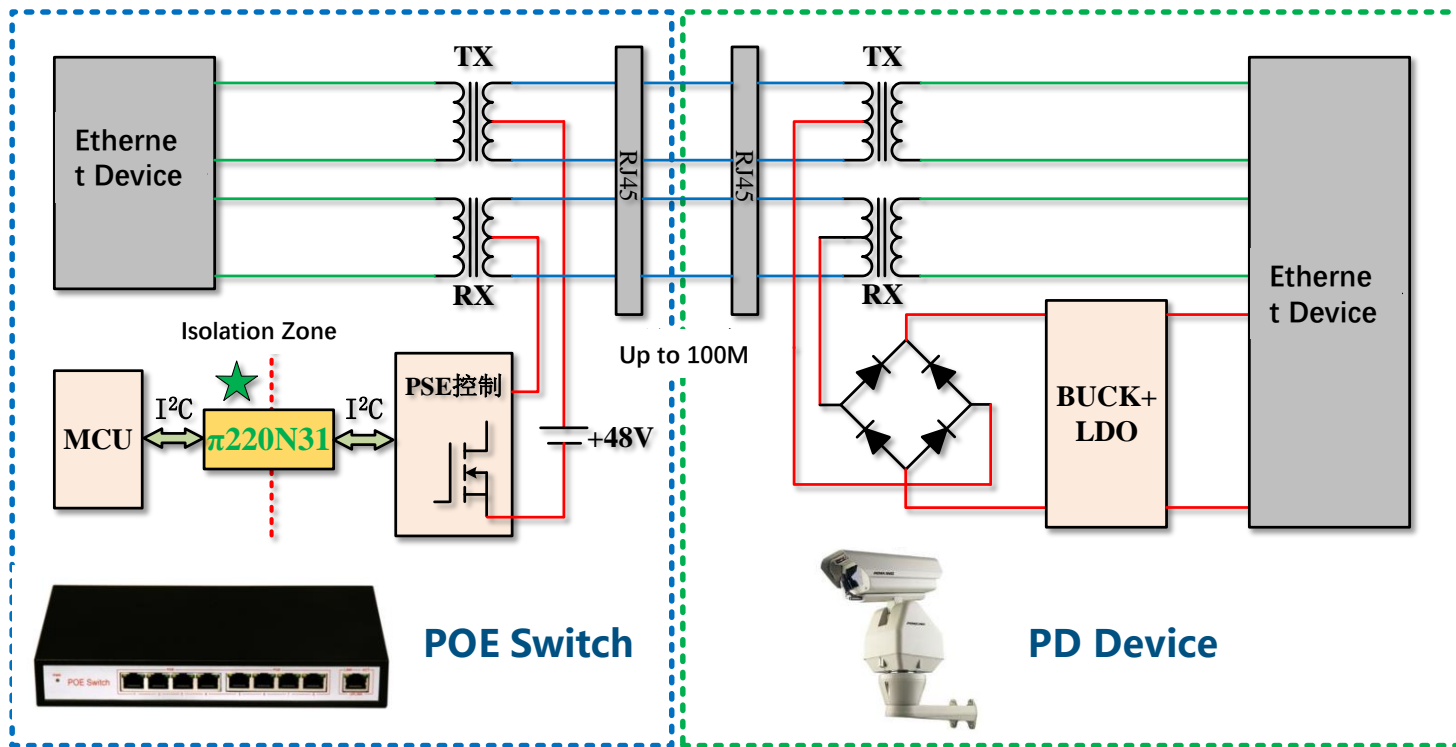
## Recommended Model:

RS485:  $\pi$ 131M31    RS232:  $\pi$ 122M31



# POE Switch

Chips create new value



The role of isolator : Isolated I2C communication between MCU and PSE

# POE Switch

Chips create new value

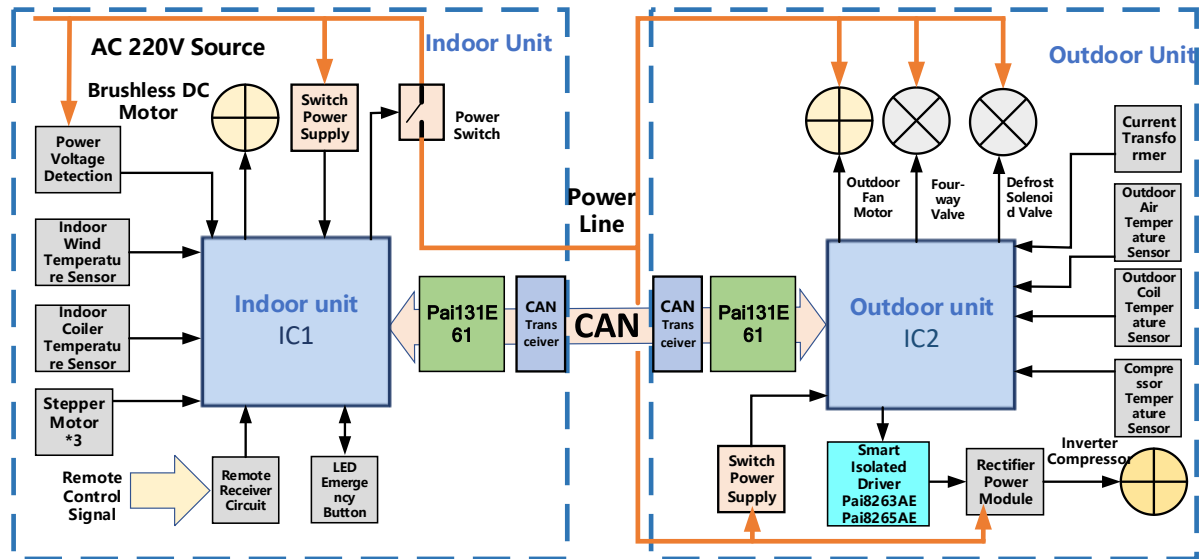
Main Market:	Benchmarking Products	Recommended Model:
POE Switch : H3C NVR: HIKVISION, DAHUA	ADI, TI, Silicon labs-I2C ADI, TI, Silicon labs-SPI Low Speed Optocoupler-UART	Pai220N31 (I2C Isolation) Pai141M61 (SPI Isolation) Pai122U31 (UART Isolation)

## Successful Cases



# Home Appliances : Commercial Air Conditioner

Chips create new value



2Pai:  $\pi 131E61$

Compatible With:

① ADI: ADuM1301

② TI: ISO7731

1. IGBT Driver Signal Isolation: Pai8263AE/8265QE (Compatible With: TLP5214A)

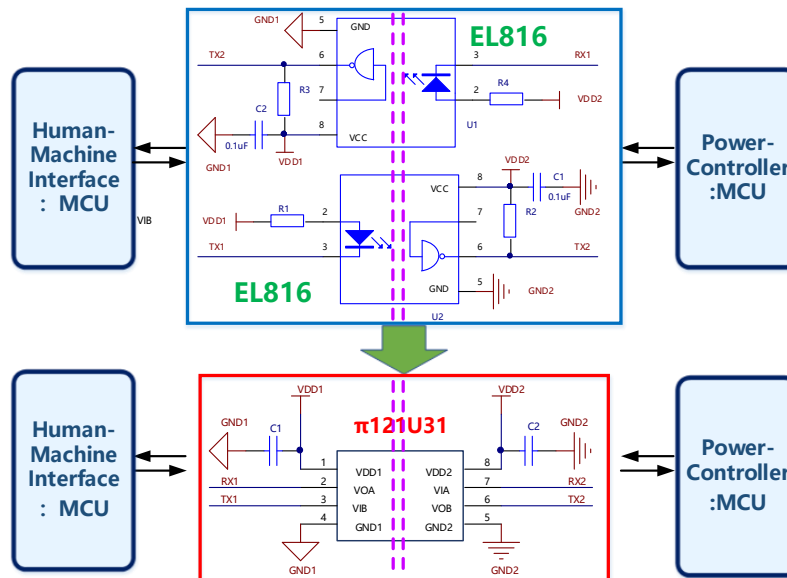
2. CAN Bus Isolation: Pai131E61

# Home Appliances : Kitchen Ventilator

Chips create new value

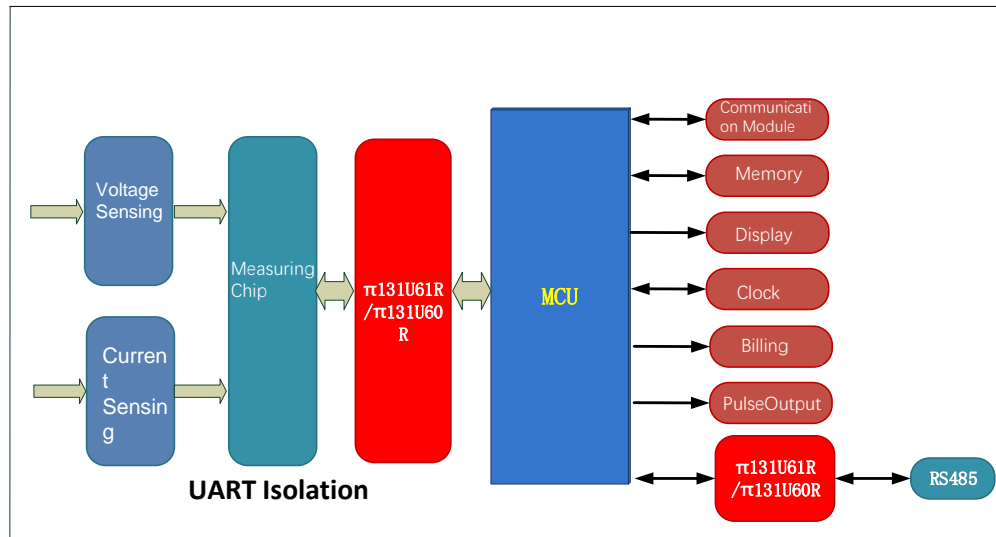
Item	Maximum data rate	Power	Temperature Drift	Working Temperature	CMTI	PCB Area
EL816*2	<30Kbps	7.5mA*2	CTR change with temperature	-40°C~85°C	<25kV/us	360mm <sup>2</sup>
π121U31	150Kbps	1.3mA	No CTR, Eliminates temperature drift	-40°C~125°C	200kV/us	120mm <sup>2</sup>

The role of isolator : Isolated UART communication between HMI and Power Controller.



# Smart Meter

Chips create new value



## The role of $\pi 131U61R$ / $\pi 131U60R$ : UART Isolation, 485 Isolation

1. Using mature CMOS technology , having good consistency, reducing debugging costs during development .
2. Under the premise of ensuring the insulation performance , patented iDivider technology , can significantly reduce the overall cost of the chip. Even compared with ordinary optocouplers,  $\pi 131U61R$ ' s cost remains competitive.
3. The service life can be more than twice that of ordinary optocouplers .